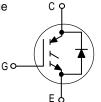
Product Preview Data Sheet

Insulated Gate Bipolar Transistor with Anti-Parallel Diode

N-Channel Enhancement Mode Silicon Gate

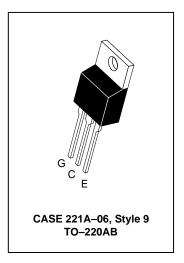
This Insulated Gate Bipolar Transistor (IGBT) is co-packaged with a soft recovery ultra-fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage blocking capability. Its new 600V IGBT technology is specifically suited for applications requiring both a high temperature short circuit capability and a low VCE(on). It also provides fast switching characteristics and results in efficient operation at high frequencies. Co-packaged IGBTs save space, reduce assembly time and cost. This new E-series introduces an Energy-efficient and short circuit rated device.

- Industry Standard TO-220 Package
- High Speed E_{off}: 44 μJ/A typical at 125°C
- High Short Circuit Capability 10 μs minimum at 125°C
- Low On-Voltage 2.0V typical at 8A, 125°C
- Soft Recovery Free Wheeling Diode is included in the package
- Robust High Voltage Termination



MGP11N60DE

IGBT & DIODE IN TO-220 11 A @ 90°C 15 A @ 25°C 600 VOLTS SHORT CIRCUIT RATED LOW ON-VOLTAGE



MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCES	600	Vdc
Collector–Gate Voltage (R _{GE} = 1.0 MΩ)	V _{CGR}	600	Vdc
Gate-Emitter Voltage — Continuous	V _{GE}	±20	Vdc
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	IC25 IC90 ICM	15 11 30	Adc Apk
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	95 0.76	Watts W/°C
Operating and Storage Junction Temperature Range	TJ, T _{stg}	-55 to 150	°C
Short Circuit Withstand Time (V_{CC} = 360 Vdc, V_{GE} = 15 Vdc, T_J = 125°C, R_G = 20 Ω)	t _{SC}	10	μs
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R _θ JC R _θ JC R _θ JA	1.32 tbd 65	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C
Mounting Torque, 6–32 or M3 screw	10 lbf•in (1.13 N•m)		

⁽¹⁾ Pulse width is limited by maximum junction temperature.

This document contains information on a new product. Specifications and information are subject to change without notice.



MGP11N60DE

ELECTRICAL CHARACTERISTICS (T_{.J} = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS							
Collector–to–Emitter Breakdown Voltage (VGE = 0 Vdc, I _C = 250 μAdc) Temperature Coefficient (Positive)		BVCES	600 —	 870	_	Vdc mV/°C	
Zero Gate Voltage Collector Current (VCE = 600 Vdc, VGE = 0 Vdc) (VCE = 600 Vdc, VGE = 0 Vdc, TJ = 125°C)		ICES		_	100 2500	μAdc	
Gate–Body Leakage Current (V _{GE} = ± 20 Vdc, V _{CE} = 0 Vdc)		IGES	_	_	250	nAdc	
ON CHARACTERISTICS (1)		•	•			•	
Collector-to-Emitter On-State Voltage (VGE = 15 Vdc, I _C = 4 Adc) (VGE = 15 Vdc, I _C = 4 Adc, T _J = 125°C) (VGE = 15 Vdc, I _C = 8 Adc)		VCE(on)	_ _ _	1.57 1.45 2.01	2.05 — 2.75	Vdc	
Gate Threshold Voltage (VCE = VGE, IC = 1 mAdc) Threshold Temperature Coefficient (Negative)		VGE(th)	4.0 —	6.0 10	8.0 —	Vdc mV/°C	
Forward Transconductance (V _{CE} = 10 Vdc, I _C = 8 Adc)		9fe	_	tbd	_	Mhos	
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ies}	_	tbd	-	pF	
Output Capacitance	(V _{CE} = 25 Vdc, V _{GE} = 0 Vdc, f = 1.0 MHz)	C _{oes}	_	tbd	_]	
Transfer Capacitance]	C _{res}	_	tbd	_		
SWITCHING CHARACTERISTICS (1)	•					
Turn-On Delay Time	(Van - 360 Vda Ia - 9 Ada	^t d(on)	_	tbd	_	ns	
Rise Time	V _{GE} = 360 Vdc, I _C = 8 Adc, V _{GE} = 15 Vdc, L = 300 μH	t _r	_	tbd	-		
Turn-Off Delay Time	$R_G = 20 \Omega$, $T_J = 25^{\circ}C$) Energy losses include "tail"	td(off)	_	tbd	_]	
Fall Time	Lifergy losses include tall	t _f	_	tbd	_]	
Turn-Off Switching Loss		E _{off}	_	0.23	0.38	mJ	
Turn-On Switching Loss		Eon	_	0.27	_		
Total Switching Loss		E _{ts}	_	0.50	_		
Turn-On Delay Time	// 000 V/d- 1 0 A d-	^t d(on)	_	tbd	_	ns	
Rise Time	V _{GE} = 360 Vdc, I _C = 8 Adc, V _{GE} = 15 Vdc, L = 300 μH	t _r	_	tbd	_	1	
Turn-Off Delay Time	$R_G = 20 \Omega, T_J = 125^{\circ}C$	td(off)	_	tbd	_	1	
Fall Time	Energy losses include "tail"	t _f	_	tbd	_	1	
Turn-Off Switching Loss	1	E _{off}	_	0.35	_	mJ	
Turn-On Switching Loss	1	Eon	_	0.48	_	1	
Total Switching Loss	1	E _{ts}	_	0.83	_	1	
Gate Charge		QT	_	tbd	_	nC	
	(V _{CC} = 360 Vdc, I _C = 8 Adc, V _{GE} = 15 Vdc)	Q ₁	_	tbd	_	1	
		Q ₂	_	tbd	_	1	

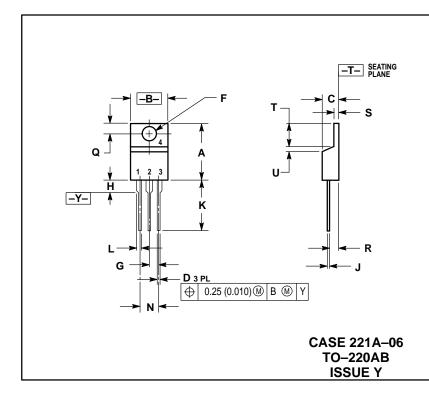
2 Motorola IGBT Device Data

Characteristic		Symbol	Min	Тур	Max	Unit	
DIODE CHARACTERISTICS							
Diode Forward Voltage Drop (IEC = 4 Adc) (IEC = 4 Adc, T _J = 125°C) (IEC = 8 Adc)		VFEC	_ _ _	tbd tbd tbd	tbd — tbd	Vdc	
Reverse Recovery Time	(I _F = 8 Adc, V _R = 360 Vdc, dI _F /dt = 200 A/μs)	t _{rr}	_	tbd	_	ns	
		ta	_	tbd	_		
		t _b	_	tbd	_		
Reverse Recovery Stored Charge		Q _{RR}	_	tbd	_	μС	
Reverse Recovery Time	(I _F = 8 Adc, V _R = 360 Vdc, dI _F /dt = 200 A/μs, T _J = 125°C)	t _{rr}	_	tbd	_	ns	
		ta	_	tbd	_		
		t _b	_	tbd	_		
Reverse Recovery Stored Charge		Q _{RR}	_	tbd	_	μС	
INTERNAL PACKAGE INDUCTANCE							
Internal Emitter Inductance (Measured from the emitter lead 0.25" from package to emitter bond pad)		LE	_	7.5	_	nΗ	

⁽¹⁾ Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

Motorola IGBT Device Data 3

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INCHES N		MILLIM	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.560	0.625	14.23	15.87		
В	0.380	0.420	9.66	10.66		
С	0.140	0.190	3.56	4.82		
D	0.020	0.045	0.51	1.14		
F	0.139	0.155	3.53	3.93		
G	0.100 BSC		2.54 BSC			
Н	_	0.280		7.11		
J	0.012	0.045	0.31	1.14		
K	0.500	0.580	12.70	14.73		
L	0.045	0.070	1.15	1.77		
N	0.200 BSC		5.08 BSC			
Q	0.100	0.135	2.54	3.42		
R	0.080	0.115	2.04	2.92		
S	0.020	0.055	0.51	1.39		
Т	0.235	0.255	5.97	6.47		
U	0.000	0.050	0.00	1.27		

PIN 1. GATE

- COLLECTOR
- 3. EMITTER
- 4. COLLECTOR

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